

Bondline™ 2258 is an electrically and thermally conductive semiconductor grade adhesive. This stress absorbing, silver filled epoxy is designed for bonding chips to substrates with a mismatch in coefficient of thermal expansion. Cure temperature as low as 70°C.

*“A Reliable
and Responsive
Adhesive
Company.”*

Adhesive Properties

Color:	Silver
Viscosity*:	14,000 cps (+/- 2,000 cps)
Work Life @ 25°C:	4 hours
Hardness (Shore D):	47
Cure Options:	1 hour @ 125°C or 1.5 hours @ 100°C or 3 hours @ 70°C
Service Temperature Range:	-55°C to 125°C
Lap Shear Strength @ 25°C (Al to Al):	800 psi
Specific Gravity:	3.9
Weight Loss @ 85°C:	0.025%
@ 105°C:	0.031%
Volume Resistivity:	.0002 ohm cm
Young's Modulus:	1 x 10 ⁴ psi (ASTM D638-98, Type I)
Strain at break:	30% (ASTM D638-98, Type I)
Thermal Conductivity:	6.9 W/mK
Mobile Ion Concentration:	
Chloride:	60ppm
Sodium:	25ppm
Potassium:	Nil
Glass Transition Temperature (Tg)**:	15°C
Coefficient of Thermal Expansion**:	
Above Tg:	198 x 10 ⁻⁶ in/in/°C
Shelf Life:	6 Months
Storage:	Store at -40°C or Colder
Availability:	Net volume 1cc to 5cc, available in disposable 3cc & 5cc syringes.

Adhesive properties are not intended to be used as specification limits.

* Brookfield DV-II+ (Cone & Plate), Spindle CP51, 25°C, 5 rpm

** Cured 1 hour @ 100°C

Bondline™

Electronic Adhesives, Inc.

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General Instructions for Adhesive Storage and Use

FROZEN STORAGE – *Unless otherwise stated*

This adhesive must be stored at (minus) –40°C (°F) or colder at all times. Storing this adhesive at temperatures warmer than (minus) –40°C (°F) may alter the adhesives' properties and shorten its work life. DO NOT RE-FREEZE adhesive that has already been thawed!

THAWING PROCESS

Adhesive must reach room temperature before use. Remove syringes from freezer. Place syringes on end for thawing. See chart below for thaw time based on syringe size.

SYRINGE SIZE	THAW TIME
1cc	5 minutes
3cc	10 minutes
5cc	15 minutes
10cc	20 minutes

**** NOTE:** To accelerate thaw time, place syringes in front of an air blower or fan. This will reduce the thaw time by approximately 50%. Remove all condensation from syringes prior to use.

SURFACE PREPARATION

Make sure that all surface areas to be bonded are free of any contamination. If parts have been solvent cleaned make sure solvent is dried before applying adhesive

APPLICATION

Check the work life of the adhesive, on the technical data sheet. Adhesives must be used within the work life time period. The adhesives' properties will change (usually thicken) if it is used past the allowable work life.

Apply adhesive using dispensing equipment of choice. Contact Bondline Technical Service with questions about dispensing adhesives.

CURE

Choose a Cure Option (time & temperature) from the Bondline technical data sheet. Preheat the oven to the temperature of the selected cure option. For optimum cure, do not deviate from the selected cure option. Be sure to allow additional time for holding fixtures to reach cure temperature. Avoid opening oven doors during cure. Large fixtures and/or multiple fixtures may require extended cure time.

SAFETY

Review the adhesive Material Safety Data Sheet (MSDS) before using. Refer to the MSDS in case of emergency. Always wear protective gloves and goggles while handling adhesives. Only work with adhesives in well-ventilated areas, with curing ovens vented outside. For industrial use only.

TECHNICAL SERVICE CONTACT

For recommendations and help with any aspect of adhesive applications please contact the Bondline Technical Service Department (408) 830-9200, or via email: info@bondline.net or visit our website, www.bondline.net

CAUTION: For industrial use only. People with sensitive skin may have a reaction to this adhesive. Avoid skin contact. Wash all areas with soap and water immediately if contact does occur. It is important to refer to Material Safety Data Sheet (MSDS) OSHA for more details.

Bondline™
Electronic Adhesives, Inc.

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